



SOT1895-1

plastic, thermal enhanced super thin quad flat package; no leads; 24 terminals; 2.0 mm x 2.0 mm x 0.35 mm body

12 July 2017

Package information

1. Package summary

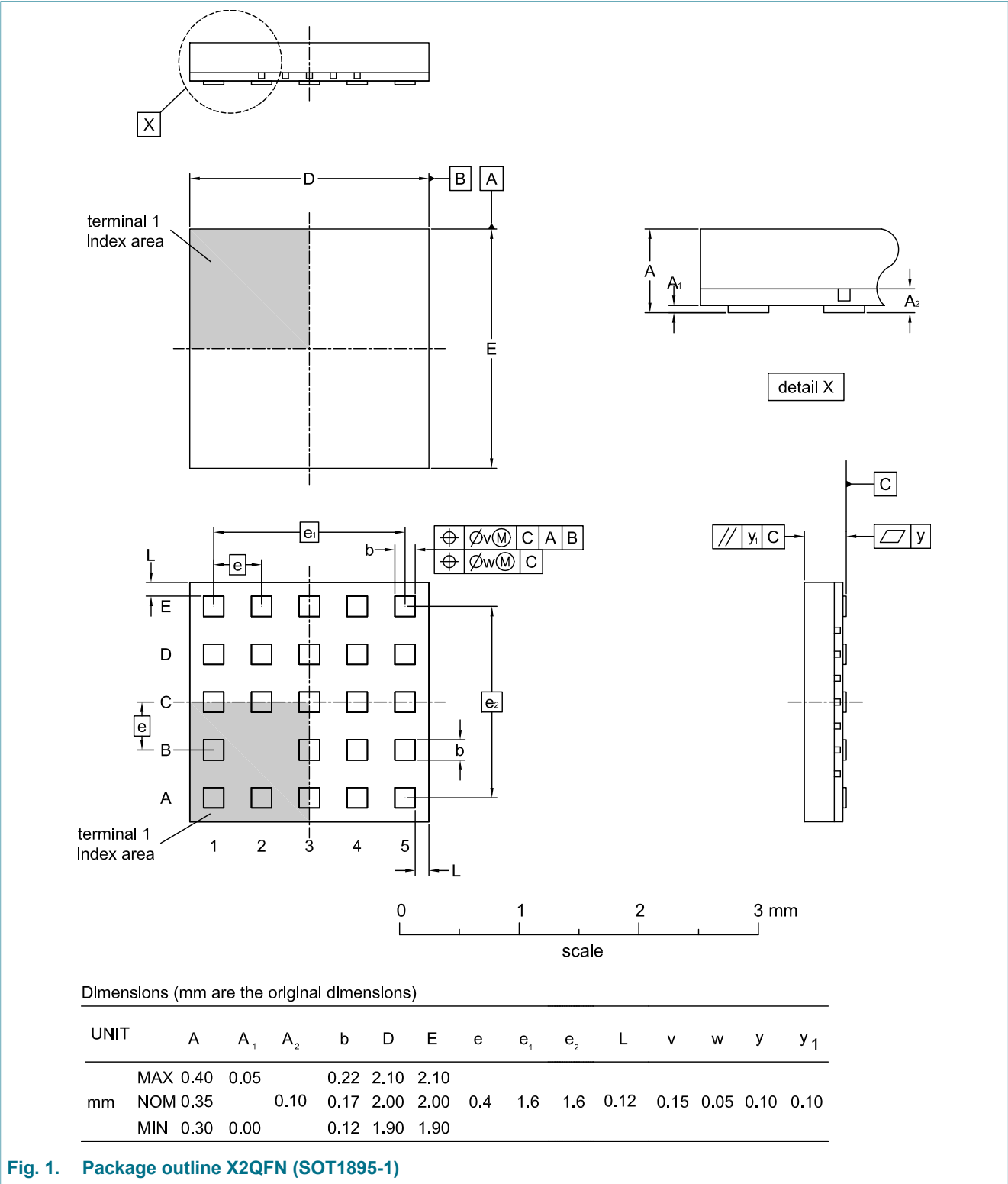
Terminal position code	B (bottom)
Package type descriptive code	X2QFN24
Package type industry code	X2QFN
Package style descriptive code	XQFN (extremely thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	19-8-2016
Manufacturer package code	SOT1895

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		1.9	-	2	2.1	mm
E	package width		1.9	-	2	2.1	mm
A	seated height		0.3	-	0.35	0.4	mm
A ₂	package height		-	-	0.1	-	mm
e	nominal pitch		-	-	0.4	-	mm
n ₂	actual quantity of termination		-	-	24	-	



2. Package outline



3. Soldering

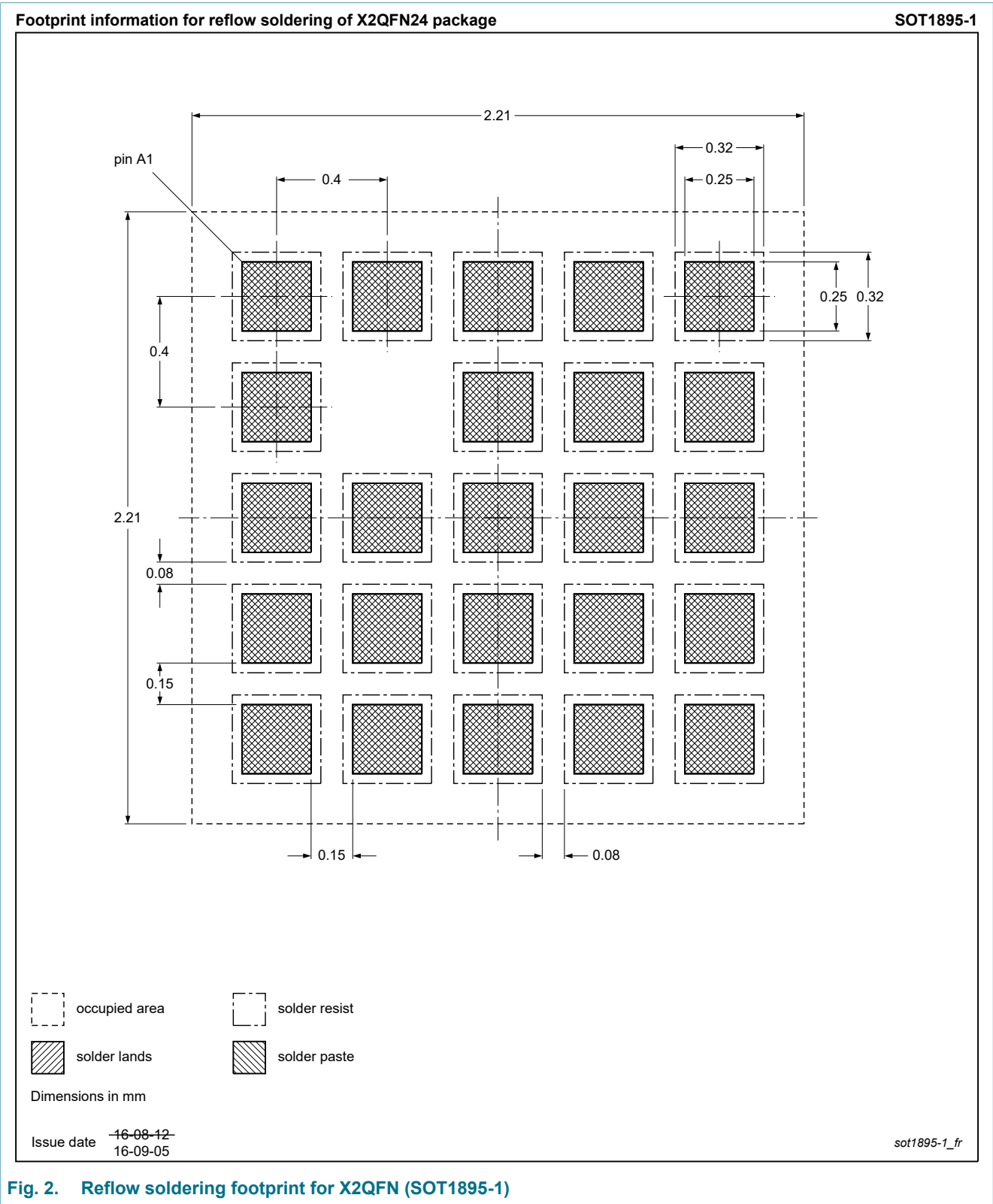


Fig. 2. Reflow soldering footprint for X2QFN (SOT1895-1)

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4. Legal information

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